L Number	Hits	Search Text	DB	T.T:
38	1514	borate adj salt	USPAT;	Time stamp
				2003/07/22 13:31
l			US-PGPUB;	
	l		EPO; JPO;	
			DERWENT;	
39	427739	amine	IBM_TDB	2002/05/20 10 10
			USPAT;	2003/07/22 13:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
40	2	(capture or capturing) near2 (protonic adj acid)	IBM_TDB	2002/07/02 12 02
		(Freedoms and asia)	USPAT;	2003/07/22 13:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
41	37934	(polymer or resin or copolymer) near10 (carboxyl)	IBM_TDB	2002/02/22 12 2
		(emboxy)	USPAT;	2003/07/22 13:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
42	383260	(polymer or resin or copolymer) near10 (carboxyl or acid)	IBM_TDB USPAT;	2002/07/22 12 24
		1 y many manufacture (components) of acidy	US-PGPUB;	2003/07/22 13:34
			EPO; JPO;	
ľ			DERWENT;	
			IBM TDB	
43	134803	(polymer or resin or copolymer) near10 (unsaturation or unsaturated or	USPAT;	2003/07/22 13:36
	İ	double adj bond)	US-PGPUB;	2003/07/22 13:30
ĺ	1		EPO; JPO;	•
	i		DERWENT;	
			IBM_TDB	
45	110	(borate adj salt) and amine and ((polymer or resin or copolymer) near10	USPAT;	2003/07/22 13:36
		(carboxyl or acid)) and ((polymer or resin or copolymer) near10	US-PGPUB;	2003/01/22 13:30
	1	(unsaturation or unsaturated or double adj bond))	EPO; JPO;	
		• "	DERWENT;	İ
. 1			IBM TDB	
44	19	(borate adj salt) and amine and ((polymer or resin or copolymer) near10	USPAT;	2003/07/22 13:36
		(carboxyl)) and ((polymer or resin or copolymer) near 10 (unsaturation or	US-PGPUB;	2003/01/22 13:30
	1	unsaturated or double adj bond))	EPO; JPO;	1
	1		DERWENT;	
			IBM_TDB	

L Number			DB	Tr:
38	1514	4 borate adj salt		Time stamp
			USPAT;	2003/07/22 13:3
	1		US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
39	427739	amine	IBM_TDB	
			USPAT;	2003/07/22 13:3:
	ĺ		US-PGPUB;	
	1		ЕРО; ЛРО;	
	l		DERWENT;	
40	2	(capture or capturing) near2 (protonic adj acid)	IBM_TDB	
		(capture of capturing) hear 2 (protonic adj acid)	USPAT;	2003/07/22 14:01
			US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
41	37934	(nolymer or regin or constant)	IBM_TDB	
	0.55.	(polymer or resin or copolymer) near10 (carboxyl)	USPAT;	2003/07/22 13:34
			US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
42	383260	(nolymor as as a	IBM_TDB	
	363200	(polymer or resin or copolymer) near10 (carboxyl or acid)	USPAT;	2003/07/22 13:34
			US-PGPUB;	2003/01/22 13.34
		·	EPO; JPO;	
1			DERWENT;	
43	134803	(malaure	IBM_TDB	
13	134603	(polymer or resin or copolymer) near10 (unsaturation or unsaturated or	USPAT;	2003/07/22 13:36
ļ		double adj bond)	US-PGPUB;	2003/01/22 13:36
			EPO; JPO;	
			DERWENT;	
15	110		IBM TDB	
*3	1 '	(borate adj salt) and amine and ((polymer or resin or copolymer) near10 (carboxyl or acid)) and ((polymer or resin or copolymer) near10	USPAT;	2003/07/22 13:36
1			US-PGPUB;	2003/07/22 13:36
[(unsaturation or unsaturated or double adj bond))	EPO; JPO;	
	ľ	,	DERWENT;	
4	,,	4	IBM_TDB	
	19	(borate adj salt) and amine and ((polymer or resin or copolymer) near10	USPAT;	2002/07/22 12 26
1		(carboxy)) and ((polymer or resin or conclumer) nearly (uncertainty	US-PGPUB;	2003/07/22 13:36
ļ	ł	unsaturated or double adj bond))	EPO; JPO;	
	- 1		DERWENT;	
6	105		IBM_TDB	
١ ا	106	(capture or capturing) near3 (protonic or proton or hydrogen adj atom)		2002/07/20 14 00
i	ļ	i ay Beni adj atom)		2003/07/22 14:02
			US-PGPUB;	
			EPO; JPO;	
,	. 1		DERWENT;	1
7	1	(borate adj salt) and ((capture or capturing) near3 (protonic or proton or	IBM_TDB	2000 107 10
	1	hydrogen adj atom))	USPAT;	2003/07/22 14:02
			US-PGPUB;	
			EPO; JPO;	ŀ
			DERWENT;	
			IBM TDB	

L Number	Hits	Search Text	DB	Time stamp
1	1514	borate adj salt	USPAT;	2003/07/22 12:34
-		•	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	2002/07/22 12:22
2	23961	(polymer or resin) near5 carboxyl	USPAT; US-PGPUB;	2003/07/22 12:32
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
3	98893	(polymer or resin) near10 (unsaturated or unsaturation)	USPAT;	2003/07/22 12:24
	, , , ,	(4-3)	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
			IBM_TDB USPAT;	2003/07/22 12:33
4	411588	phenyl	US-PGPUB;	2003/07/22 12.33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	4	(borate adj salt) and ((polymer or resin) near5 carboxyl) and ((polymer or	USPAT;	2003/07/22 12:22
		resin) near10 (unsaturated or unsaturation)) and phenyl	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM_TDB	
	107100	(polymer or resin) near10 (unsaturated or unsaturation or double adj bond)	USPAT;	2003/07/22 12:32
6	107199	(polymer or resin) near to (unsaturated of unsaturation of double adjubble)	US-PGPUB;	2003/07/22 12/02
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
7	45472	(polymer or resin) near7 (unsaturated or unsaturation or double adj bond)	USPAT;	2003/07/22 12:32
			US-PGPUB	2003/07/22 12:32
8	13623	(polymer or resin) near5 carboxyl	USPAT; US-PGPUB	2003/07/22 12.32
	218338	mhomyd	USPAT;	2003/07/22 12:33
9	210330	phenyl	US-PGPUB	
10	4711	430/270.1.ccls. or 430/281.1.ccls.	USPAT;	2003/07/22 12:33
			US-PGPUB	
11	238	((polymer or resin) near7 (unsaturated or unsaturation or double adj bond))	USPAT;	2003/07/22 12:33
i		and ((polymer or resin) near5 carboxyl) and phenyl and (430/270.1.ccls. or	US-PGPUB	
		430/281.1.ccls.)	USPAT;	2003/07/22 12:34
12	1218	borate adj salt	US-PGPUB	2005/07/22 12.54
13	2	(((polymer or resin) near7 (unsaturated or unsaturation or double adj bond))	USPAT;	2003/07/22 12:34
1.5		and ((polymer or resin) near5 carboxyl) and phenyl and (430/270.1.ccls. or	US-PGPUB	
		430/281.1.ccls.)) and (borate adj salt)		
14	44373	borate	USPAT;	2003/07/22 12:34
		The state of the s	US-PGPUB	2003/07/22 12:51
15	48	(((polymer or resin) near7 (unsaturated or unsaturation or double adj bond)) and ((polymer or resin) near5 carboxyl) and phenyl and (430/270.1.ccls. or	USPAT; US-PGPUB	2003/01/22 12.31
		and ((polymer or resin) nears carboxyl) and pnenyl and (430/270.1.ccis. of 430/281.1.ccis.)) and borate	001000	
16	428	borate and ((polymer or resin) near7 (unsaturated or unsaturation or double	USPAT;	2003/07/22 12:51
1.0	720	adj bond)) and ((polymer or resin) near5 carboxyl)	US-PGPUB	
18	258749	amine	USPAT;	2003/07/22 12:52
			US-PGPUB	2003/07/22 12:52
19	350		USPAT;	2003/07/22 12:52
1,7		adj bond)) and ((polymer or resin) near5 carboxyl)) and amine (430/270.1.ccls. or 430/281.1.ccls.) and (borate and ((polymer or resin)	US-PGPUB USPAT;	2003/07/22 12:56
17	63	near7 (unsaturated or unsaturation or double adj bond)) and ((polymer or	US-PGPUB	2002.07.22 12.30
		resin) near5 carboxyl))		
20	1220	, , , , , , , , , , , , , , , , , , ,	USPAT;	2003/07/22 12:57
			US-PGPUB	

1980 1980	<u> </u>	-r			
21 44	22	317		USPAT;	2003/07/22 12:57
21			double adj bond)) and ((polymer or resin) near5 carboxyl)) and amine) not		
1980	1	1			
1980 1980	21	44	((430/270.1.ccls. or 430/281.1.ccls.) and (borate and ((polymer or resin)	USPAT;	2003/07/22 12:57
1980 borate same (developer or developing) USPAT; US-PGPUB			near7 (unsaturated or unsaturation or double adj bond)) and ((polymer or	US-PGPUB	
25 302 ((borate and ((polymer or resin) near7 (unsaturated or unsaturation or double adj bond)) and ((polymer or resin) near5 (arboxyl)) and amine) not (borate same (developer or developing)) (18-PGPUB (USPAT; US-PGPUB	22		resin) near5 carboxyl))) not (borate same developer)		
25 302 ((borate and ((polymer or resin) near? (unsaturated or unsaturation or double adj bond)) and ((polymer or resin) near5 carboxyl)) and amine) not double adj bond)) and ((polymer or resin) near5 carboxyl)) and amine) not double adj bond)) and ((polymer or resin) near5 carboxyl)) and amine) not double adj bond)) and ((polymer or resin) near5 carboxyl))) not (borate amd ((polymer or resin) near5 carboxyl))) not (borate amd ((polymer or resin) near5 carboxyl))) not (borate same (developer or developing)) 26	23	1980	borate same (developer or developing)	USPAT;	2003/07/22 12:58
1	25			US-PGPUB	
24 35 (daulote adj bond)) and ((polymer or resin) near acarboxyl)) and amine) not (borate same (developen or developing)) ((430/270.1.ccls. or 430/281.1.ccls.) and (borate and ((polymer or resin) near acarboxyl))) not (borate same (developer or developing)) ((430/270.1.ccls. or 430/281.1.ccls.) and (borate and ((polymer or resin) near acarboxyl))) not (borate same (developer or developing)) (25-PGPUB US-PAT; US-PGPUB US-PAT; US-PGPUB; US-PAT; US-PAT; US-PAT; US-PAT; US-PAT; US-PAT; US-PAT	23	302	((borate and ((polymer or resin) near7 (unsaturated or unsaturation or	USPAT;	2003/07/22 12:58
24	1		double adj bond)) and ((polymer or resin) near5 carboxyl)) and amine) not	US-PGPUB	
1	24	25	(borate same (developer or developing))		
1	24	35	((430/270.1.ccls. or 430/281.1.ccls.) and (borate and ((polymer or resin)	USPAT;	2003/07/22 13:07
26		1	near/ (unsaturated or unsaturation or double adj bond)) and ((polymer or	US-PGPUB	
27	26	1 .	resin) near5 carboxyl))) not (borate same (developer or developing))		
28	20	1	6569603.pn.	USPAT;	2003/07/22 13:08
SAPAT; 2003/07/22 13:10 2003/07/22 13:10 2003/07/22 13:10 2003/07/22 13:10 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:11 2003/07/22 13:12 2003/07/22 13:13 2003/07/22 13:13 2003/07/22 13:14 2003/07/22 13:14 2003/07/22 13:14 2003/07/22 13:15 2003/07/22 13:15 2003/07/22 13:15 2003/07/22 13:15 2003/07/22 13:15 2003/07/22 13:16 2003/07/22 13:16 2003/07/22 13:16 2003/07/22 13:16 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:18 2003/07/22 13:22 2003/07/22 13:22 2003/07/22 13:23 20	27	1 .	6114002	US-PGPUB	
1 5496685.pn. USPAT; US-PGPUB; EPO; IPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; IPO; DERWENT; US-PGPUB; EPO; IPO; IPO; DERWENT; US-PGPUB; EPO; IPO; IPO; IPO; IPO; IPO; IPO; IPO; I	1 2 '	· '	0114092.pn.		2003/07/22 13:10
29	28	1 .	E407705	US-PGPUB	
29	20	1	3490085.pn.	USPAT;	2003/07/22 13:10
1	20		5413963		
30	29	1	3413803.pn.	USPAT;	2003/07/22 13:11
31	30	1	5206112		
1 5153095.pn. USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; E	1 30	1	1 3200113.pn.	,	2003/07/22 13:12
1 4701399.pn. 2003/07/22 13:13 US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; D	31	1	5153005 nn		
32	1.	1	5 15 5 0 9 5 .pm.		2003/07/22 13:13
1 4603103.pn. US-PGPUB EPO; IPO; DERWENT; IBM_TDB US-	32	1	4701300 pp	A CONTRACTOR OF THE CONTRACTOR	
1 1524 (capture or capturing) near2 acid USPAT; US-PGPUB USPAT; US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; IPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; IPO; DERWENT; IPO;	32	1	4701393.pii.	1	2003/07/22 13:14
1 1524 (capture or capturing) near2 acid USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	33	1 1	4603103 pp	1	
1524 (capture or capturing) near2 acid USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	1	1 1	1005105.pm.	,	2003/07/22 13:15
35 2 (capture or capturing) near2 (protonic adj acid) US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; EPO; J	34	1524	(capture or capturing) pear? acid	1	
2 (capture or capturing) near2 (protonic adj acid) EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;]	(supraire of cupturing) hearz actu	1	2003/07/22 13:16
35 2 (capture or capturing) near2 (protonic adj acid) DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; US-					
35 2 (capture or capturing) near2 (protonic adj acid) IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB;					
1 1 1 1 2 2 2 2 2 2		1		1	
US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; D	35	2	(capture or capturing) near? (protonic adjacid)	_	2002/07/20
36]	(2003/07/22 13:18
36		1			
36					
37 2 5308888.pn. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGP				•	}
37 2 5308888.pn. US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT;	36	1	jp-53002403-\$.did.		2002/07/20 12 20
EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;					2003/07/22 13:22
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; DERWENT;					1
37 2 5308888.pn. IBM_TDB					
37 2 3308888.pn. USPAT; US-PGPUB; EPO; JPO; DERWENT;					ĺ
US-PGPUB; EPO; JPO; DERWENT;	37	2	5308888.pn.		2002/07/22 12:22
EPO; JPO; DERWENT;			-		2003/07/22 13:23
DERWENT;		1		- 1	
		1			

L3 ANSWER 11 OF 25 CAPLUS COPYRIGHT 2003 ACS on STN

1978:190411 CAPLUS AN

DN 88:190411

Capturing protonic acids ΤI

IN Mukoyama, Mitsuaki; Kobayashi, Susumu

PA Tokyo Kasei Kogyo K. K., Japan

SO Jpn. Kokai Tokkyo Koho, 2 pp.

CODEN: JKXXAF Patent

LA Japanese

FAN.CNT 1

DT

PATENT NO. KIND DATE APPLICATION NO. DATE --------------______ JP 53002403 A2 19780111 JP 1976-76512 19760630 PRAI JP 1976-76512 19760630

In the prepn. of esters, acid amides, lactones, ethers, or amines from carboxylic acids, alcs., amines, or alkyl halides by condensation with release of a protonic acid, the protonic acid was captured by neutral or slightly basic compds. I (R,R1-R4 = H, alkyl, alkenyl, cyclohexyl, aryl, aralkyl; R1R2, R3R4 may form a ring) to increase the yield. Thus, 1 mmol PhCH2CO2H and 1 mmol PhCH2OH in CH2Cl2 was treated with a soln. of 1.2 mol 1-methyl-2-chloropyridinium iodide and 2.4 mmol I (R-R4 = H) (II) in CH2Cl2 3 h at room temp. and the ppts. (II.HCl and II.HI) filtered to give 96% PhCH2CO2CH2Ph. N-butylphenylacetamide was similarly prepd.

IT 5439-14-5

RL: RCT (Reactant); RACT (Reactant or reagent)

(catalysts for condensation reactions to remove protonic acids)

RN 5439-14-5 CAPLUS

CN2H-Pyrido[1,2-a]pyrimidin-2-one, 3,4-dihydro- (6CI, 7CI, 9CI) NAME)

$$\bigcup_{N} \bigcap_{0} O$$

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09/771568 = 5009 6569403

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L8
    ANSWER 1 OF 7 CAPLUS COPYRIGHT 2003 ACS on STN
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AN 2001:643385 CAPLUS

DN 135:218728

Light-sensitive composition and method for forming relief image using said ΤI composition

IN Furukawa, Akira

PA Japan

SO U.S. Pat. Appl. Publ., 30 pp. CODEN: USXXCO

DT

Patent

LA English

FAN.CNT 1

		PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
J	ΡI	US 2001018164	A1	20010830	US 2001-771568	20010130
		US 6569603	B2	20030527		
		JP 2001290271	A2	20011019	JP 2000-223304	20000725
		DE 10103964	A1	20011018	DE 2001-10103964	
I	PRAI	JP 2000-21475	Α	20000131		20010150
		JP 2000-223304	Α	20000725		
-	-					

AB The invention relates to a light-sensitive compn. for forming a relief image by using a scanning exposure device such as a laser, and to a compn. suitable for forming a lithog. printing plate, a resist for forming a printed circuit, a color filter or a phosphor pattern. The light-sensitive compn. comprises (a) a polymer having a Ph group substituted by a vinyl group at a side chain, (b) a photopolymn. initiator and (c) a sensitizer which sensitizes the photo-polymn. initiator, or a light-sensitive compn. which comprises (A') a polymer, the above-mentioned (b) and (c), and (d) a monomer having .gtoreq.2 Ph groups each of which is substituted by a vinyl group in the mol. of the monomer; and a method of forming a relief image which comprises coating the light-sensitive compn. as mentioned above on a support, exposing the compn. by exposure or scanning exposure and developing the same to form a relief image on the support.

IT 357384-13-5

> RL: DEV (Device component use); NUU (Other use, unclassified); POF (Polymer in formulation); USES (Uses)

(lithog. printing plate having light-sensitive coating compn. contg. polymer for forming relief image)

RN357384-13-5 CAPLUS

2-Propenoic acid, polymer with 4-ethenylphenyl 2-propenoate (9CI) CNINDEX NAME)

CM 1

CRN 111791-30-1 CMF C11 H10 O2

CM

CRN 79-10-7 C3 H4 O2 CMF

L8 ANSWER 2 OF 7 CAPLUS COPYRIGHT 2003 ACS on STN

AN 1994:702255 CAPLUS

DN 121:302255

TI Fluorine-containing curable resin composition and use for printed circuit board

IN Nishimura, Shin; Nagai, Akira; Takahashi, Akio; Mukoo, Akio; Narita, Tadashi; Hagiwara, Tokio; Hamana, Hiroshi; Katagiri, Junichi

PA Hitachi, Ltd., Japan

SO U.S., 15 pp. Cont.-in-part of U.S. Ser. No. 689,935. CODEN: USXXAM

DT Patent

LA English

FAN.CNT 2

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
US 5308888 JP 1989-242034 US 1991-689935	A 19940503 A 19890920 A2 19910520		US 1993-20399	19930222

AB The title resin having excellent heat resistance and flame retardance after curing and showing a low dielec. const. is prepd. from a polymer contg. F or a F-contg. group [C(R1):C(R2)R3xR4y]m, wherein R1,R2 = H, F, Me and CF3; R3, R4 = CH2 and CF2; x,y = 0-4, and m = 30-1000, and a photopolymn. initiator; the compn. is a solid at ambient temp., melts 100-150.degree., has a melt velocity of .ltoreq.106 P, and is photocurable. Thus, poly(hexafluoro-1,3-butadiene) 100, benzophenone 10, Ph3N 10 parts dissolved in hexafluorbenzene gave a varnish for prepg. prepregs for laminate plates.

IT 159105-52-9

RL: USES (Uses)

(prepreg laminate for printed circuit board)

RN 159105-52-9 CAPLUS

CN 2-Propenoic acid, 4-ethenylphenyl ester, polymer with 1,1,2,3,4,4-hexafluoro-1,3-butadiene (9CI) (CA INDEX NAME)

CM 1

CRN 111791-30-1 CMF C11 H10 O2

CM 2

CRN 685-63-2 CMF C4 F6

CF₂ - C— C— F

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L8
    ANSWER 4 OF 7 CAPLUS COPYRIGHT 2003 ACS on STN
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AN 1990:516519 CAPLUS

DN 113:116519

Thermosetting resin compositions containing dicyanates or diisocyanates TI and unsaturated halogenated styrene derivative polymers, printed circuit board using the resin composition, and process for producing printed circuit board

Suzuki, Masao; Katagiri, Junichi; Nagai, Akira; Suzuki, Masahiro; IN Takahashi, Akio

Hitachi, Ltd., Japan; Hitachi Chemical Co., Ltd. PA

Eur. Pat. Appl., 22 pp. SO

CODEN: EPXXDW

DT Patent

LA English

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	EP 364785 EP 364785	A1 B1	19900425 19950301	EP 1989-118041	19890929
	R: CH, DE,	FR, GB	, IT, LI, NL,	SE	
	US 5045381	A	19910903	US 1989-413070	19890927
	JP 02167329	A2	19900627	JP 1989-252748	19890928
	JP 08026116	B4	19960313	01 1000 202740	19090926
	CA 1328528	A1	19940412	CA 1989-614073	19890928
PRAI	JP 1988-246978		19880930	21 1000 014073	19090928

Thermosetting compns. that give fiber-reinforced laminates with good fire AB resistance, low moisture absorption, and high mech. strength, useful for printed circuit boards, contain A) a dicyanate or diisocyanate having an arom. and (or) allycyclic group, B) a polymer (d.p. 5-100) of ring-halogenated vinylphenyl C2-4-alkenyl ethers or of ring-halogenated vinylphenyl esters of C2-4 unsatd. acids, and optionally, C) compds. having .gtoreq.1 N-substituted unsatd. imide group. Thus, a 50% DMF soln. contg. a 1:1 mixt. of XU-71787 (a dicyanate) and a poly(pvinyldibromophenyl methacrylate) (av. mol. wt. 6600, d.p. 20), 0.5 parts (based on resin) 2,5-bis(tert-butylperoxy)-3-hexyne radical polymn. initiator and 0.5 parts (based on resin) Co naphthenate trimerization catalyst for the dicyanate was impregnated in a glass fabric and dried 10 min at 150.degree. to give a prepreg and pressing 20 of these prepregs at 30 kg/cm2 for 40 min at 130.degree., 60 min at 170.degree., and 60 min at 200 degree. gave a board with dielec. const. 3.2 (1 MHz), thermal expansion coeff. 7 .times. 10-5/.degree., UL-94 flame resistance value V-0, and Cu foil peel strength 1.2 kg/cm2. Sep., the above-described DMF soln. was applied to a PET sheet, dried 10 min at 150.degree., and press-molded at 30 kg/cm2 for 40 mins at 130.degree., 60 mins at 170.degree., and 60 mins at 200.degree. to give a plate with dielec. const. 3.1 (1 MHz) bending strength 13.2 and 8.3 kg/mm2 at room temp. and 180.degree., resp., thermal decompn. initiation temp. 340.degree., and moisture absorption 1% (JIS-C-6481, 65.degree., relative humidity 95%).

IT 129114-37-0P 129114-41-6P 129114-44-9P

RL: PREP (Preparation)

(manuf. of, as glass fabric-reinforced fire- and moisture-resistant laminates for printed circuit boards)

129114-37-0 CAPLUS RN

2-Propenoic acid, bromo-4-ethenylphenyl ester, polymer with CN(1-methylethylidene)di-4,1-phenylene dicyanate (9CI) (CA INDEX NAME) CRN 129114-36-9 CMF C11 H9 Br O2 CCI IDS

$$H_2C = CH - C - O$$
 $CH = CH_2$

D1-Br

CM 2

CRN 1156-51-0 CMF C17 H14 N2 O2

RN 129114-41-6 CAPLUS
CN 2-Propenoic acid, dibromo-4-ethenylphenyl ester, polymer with XU 71787
(9CI) (CA INDEX NAME)

CM 1

CRN 129114-40-5 CMF C11 H8 Br2 O2 CCI IDS

$$H_2C = CH - C - O$$

$$CH = CH_2$$

2 (D1-Br)

CM 2

CRN 120026-65-5 CMF Unspecified CCI PMS, MAN

*** STRUCTURE DIAGRAM IS NOT AVAILABLE ***
RN 129114-44-9 CAPLUS

2-Propenoic acid, dibromo-4-ethenylphenyl ester, polymer with CN 1,1'-(1-methylethylidene)bis[4-isocyanatobenzene] (9CI) (CA INDEX NAME)

CM

CRN 129114-40-5 CMF C11 H8 Br2 O2 CCI IDS

$$^{\rm O}_{\rm H_2C=CH-C-O}$$

2 (D1-Br)

CM 2

CRN 2470-48-6 CMF C17 H14 N2 O2

ANSWER 6 OF 7 CAPLUS COPYRIGHT 2003 ACS on STN $rac{1}{8}$

AN1985:479504 CAPLUS

DN103:79504

Resist adhesion improving agents TI

PA Nippon Zeon Co., Ltd., Japan

SO Jpn. Kokai Tokkyo Koho, 6 pp. CODEN: JKXXAF

DT Patent

LA Japanese

FAN.CNT 1

ΡI

PATENT NO. KIND DATE APPLICATION NO. DATE --------------JP 60070437 A2 19850422 JP 1983-178817 19830927

PRAI JP 1983-178817 19830927

Title agents for the adhesion of resists with substrates have, as the effective component, a polymer contg. I (R,R1 = H, substituent; R2 = OH, SH; m,n = 1-5). The adhesion improving agents give excellent adhesion of resists with substrates. Thus, a Si wafer was coated with polybutadiene contg. hydroxybis(4-dimethylaminophenyl)methyl groups at the end positions, heat-treated, and then coated with a poly(vinylcinnamic acid)-type photoresist to give a photosensitive material. The material formed resist patterns by using a test pattern and was etched with a HF-NH4F mixt. to show a side etch length of 0.7 vs. 2.5 .mu. for a control having no polybutadiene subbing layer.

IT 69818-12-8

RL: USES (Uses)

(photoresist from, adhesive inner layer for, for coating on silicon wafer)

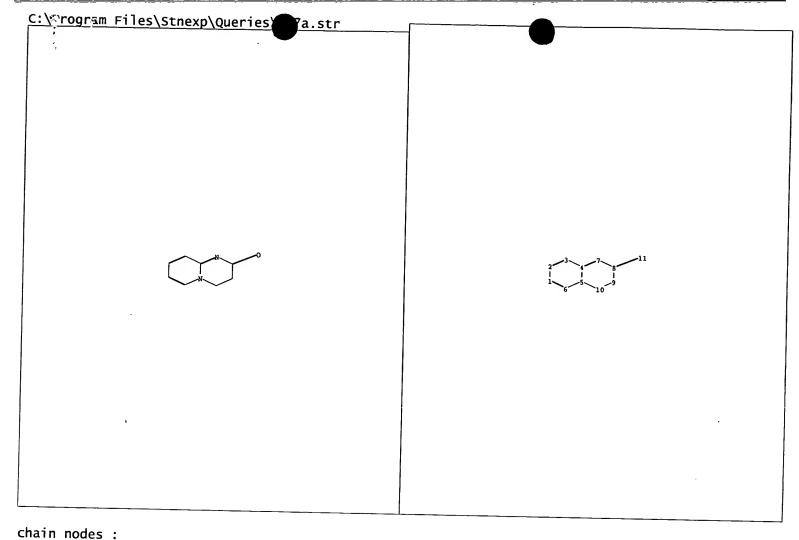
RN

69818-12-8 CAPLUS
2-Propenoic acid, 2-ethenylphenyl ester, homopolymer (9CI) (CA INDEX CN NAME)

CM 1

CRN 69804-62-2 CMF C11 H10 O2

=>



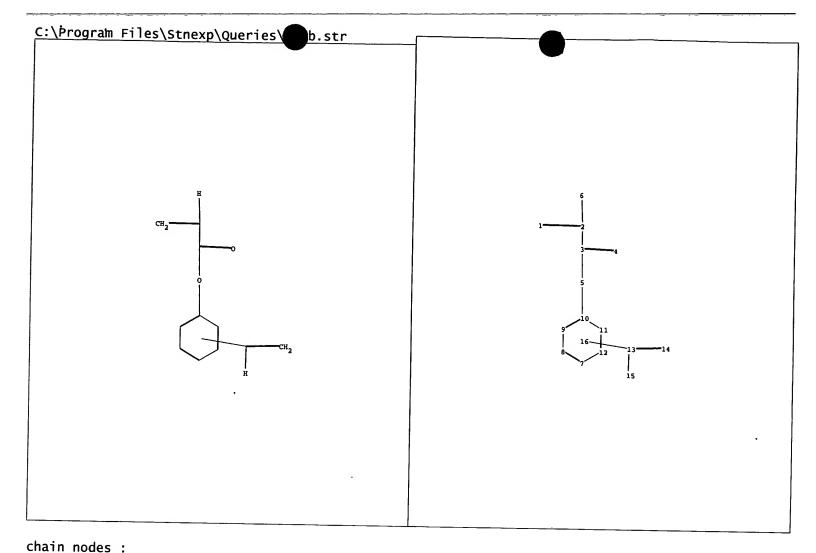
11
ring nodes:
 1 2 3 4 5 6 7 8 9 10
chain bonds:
 8-11
ring bonds:
 1-2 1-6 2-3 3-4 4-5 4-7 5-6 5-10 7-8 8-9 9-10
exact/norm bonds:
 1-2 1-6 2-3 3-4 4-5 4-7 5-6 5-10 7-8 8-9 8-11 9-10

Match level:
1:Atom 2:Atom 3:Atom 4:Atom 5:Atom 6:Atom 7:Atom 8:Atom 9:Atom 10:Atom 11:Atom

Col. 24, Line 43
Col. 24, Line 43
Col. 24, Line 43
Col. 24, Line 43
Methane) Fray Acryletti

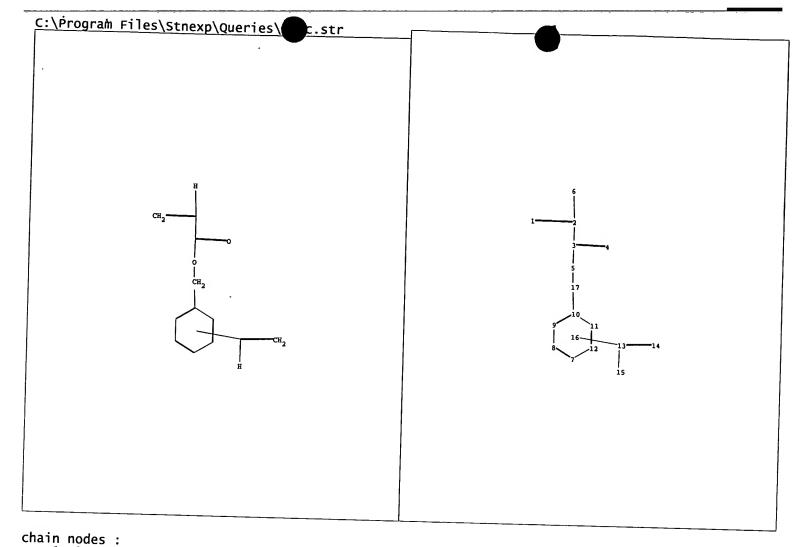
Sebacrte = 6-c+(42)8-11-0-

Chy (ils



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chain nodes:
    1 2 3 4 5 6 13 14 15
ring nodes:
    7 8 9 10 11 12
chain bonds:
    1-2 2-3 2-6 3-4 3-5 5-10 13-14 13-15
ring bonds:
    7-8 7-12 8-9 9-10 10-11 11-12
exact/norm bonds:
    3-4 3-5 5-10
exact bonds:
    1-2 2-3 2-6 13-14 13-15
normalized bonds:
    7-8 7-12 8-9 9-10 10-11 11-12
```

Match level:
1:CLASS 2:CLASS 3:CLASS 4:CLASS 5:CLASS 6:CLASS 7:Atom 8:Atom 9:Atom 10:Atom 11:Atom 12:Atom 13:CLASS 14:CLASS 15:CLASS 16:CLASS



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1 2 3 4 5 6 13 14 15 17
ring nodes:
    7 8 9 10 11 12
chain bonds:
    1-2 2-3 2-6 3-4 3-5 5-17 10-17 13-14 13-15
ring bonds:
    7-8 7-12 8-9 9-10 10-11 11-12
exact/norm bonds:
    3-4 3-5
exact bonds:
    1-2 2-3 2-6 5-17 10-17 13-14 13-15
normalized bonds:
    7-8 7-12 8-9 9-10 10-11 11-12
```

Match level:
1:CLASS 2:CLASS 3:CLASS 4:CLASS 5:CLASS 6:CLASS 7:Atom 8:Atom 9:Atom 10:Atom 11:Atom 12:Atom 13:CLASS 14:CLASS 15:CLASS 16:CLASS 17:CLASS